

MPS 2 R400 GGP

Grinding
machines

ONE MACHINE for GRINDING and POLISHING

Genauigkeits
Maschinenbau
Nürnberg GmbH



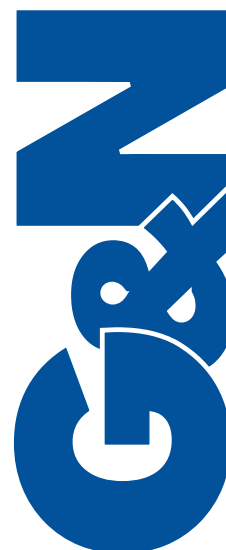
Characteristics

The MPS 2 R400 line of machines have been designed to take advantage of state-of-the-art grinding technologies and ergonomics. The fully encapsulated grinding area offers optimum environmental conditions for the operator and reduces risks of contamination.

This new version is equipped with a grinding and a polishing spindle.

Application

Grinding and polishing semiconductor material in one process.



Features

- Fully enclosed grinding area
- TWIN SPINDLE with diamond grinding wheels
- Automatic change grinding/polishing
- Temperature control during polishing process
- PLC-Control
- Measuring unit
- Automatic programs
- Vakuum chucks
- minimal TTV's
- Consistent grinding results



Technical Data

A.C. Motor	3.7 kW
Rotary Table	ø400 mm
Rotary Table Speed (infinitely variable)	0 – 30 rpm
Vacuum Chucks	porous ceramic, number depends on size
Cup Grinding Wheel	ø200x100xø76 mm or TWIN
Polishing Wheel	ø200 mm; rechargeable polishing pads
Polishing fluid	solid/liquid slurry spray nozzle
Electrical Connection	5.5 kW
Net Weight	approx. 1150 kg

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